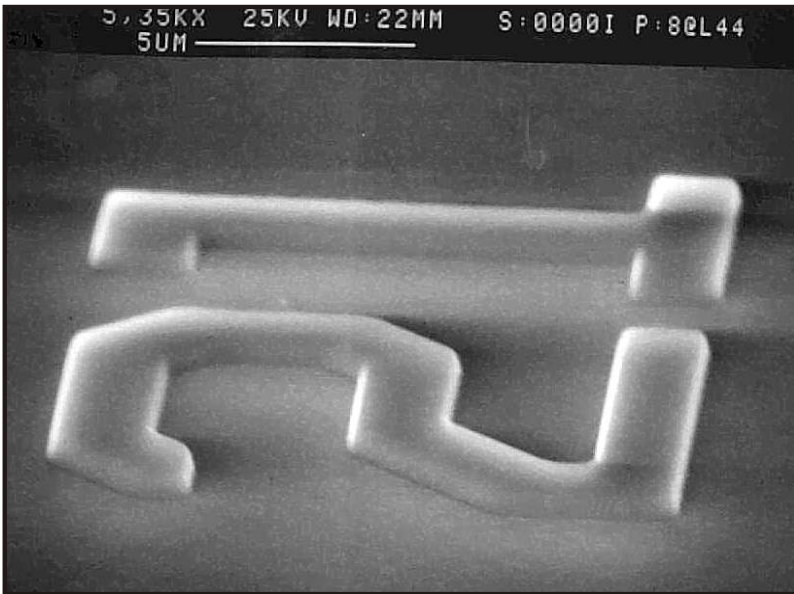


Plasmalab Data

Copper Etching for Failure Analysis



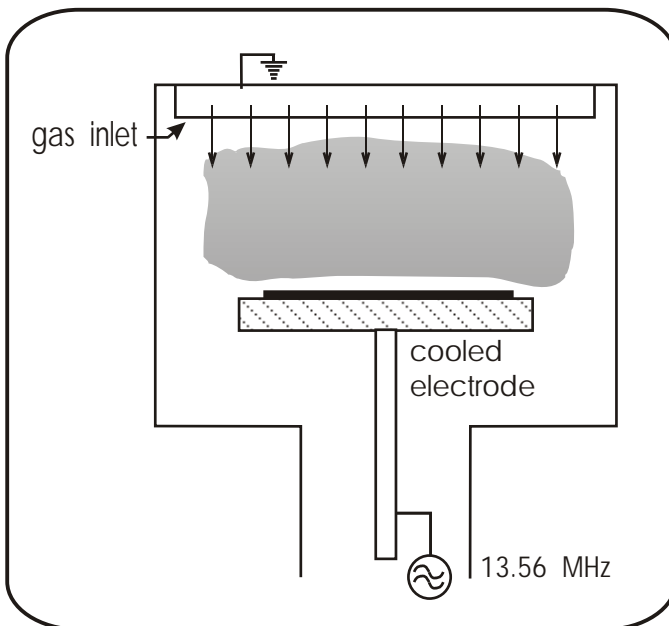
residue free copper etch



Plasmalab System 100

Plasmalab System 133

Plasmalab 80 Plus



Equipment:

- Plasmalab 80 Plus*
- Plasmalab System 100/ 133*
- (configured for Cu RIE)*

Technology:

- Parallel Plate Reactor
- Shower Head Gas inlet
- Chlorine based process

Results:

- rate : 300 nm/min (chip)
- uniformity: $\pm 5\%$ (200 mm wafer)
- residue free etch
- selectivity to SiO₂ $\geq 10 : 1$